

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ max	I_D $T_A = +25^\circ C$
-30V	8m Ω @ $V_{GS} = -10V$	-17A
	10.2m Ω @ $V_{GS} = -4.5V$	-14.5A

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

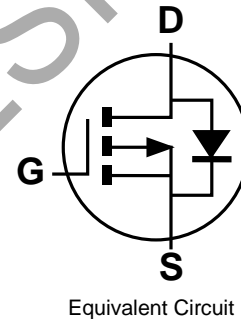
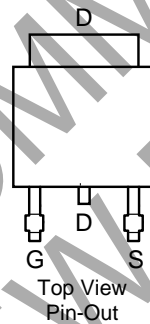
- DC-DC Converters
- Power Management Functions
- Backlighting

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—Tin Finish annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208**(3)**
- Weight: 0.33 grams (approximate)

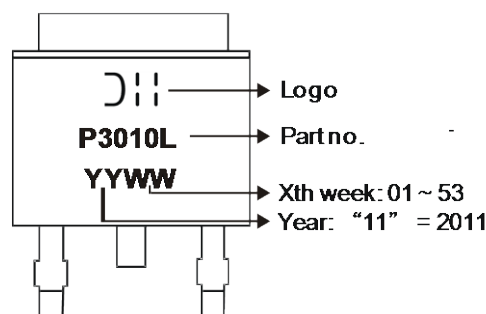


Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMP3010LK3-13	Standard	TO252	2500/Tape & Reel
DMP3010LK3Q-13	Automotive	TO252	2500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q10x qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to <https://www.diodes.com/quality/>.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

Marking Information



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	-30	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 7) V _{GS} = -10V	Steady State	T _A = +25°C T _A = +70°C	I _D	-17.0 -13.0	A
	t < 10s	T _A = +25°C T _A = +70°C	I _D	-27.0 -21.0	A
Continuous Drain Current (Note 7) V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	-14.5 -11.5	A
	t < 10s	T _A = +25°C T _A = +70°C	I _D	-23.0 -18.0	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	-100	A
Maximum Body Diode Forward Current (Note 7)			I _S	5.5	A
Avalanche Current (Note 8)			I _{AS}	47	A
Avalanche Energy (Note 8)			E _{AS}	113	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 6)		P _D	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	R _{θJA}	72	°C/W
	t < 10s		29	°C/W
Total Power Dissipation (Note 7)		P _D	3.4	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady state	R _{θJA}	37	°C/W
	t < 10s		15	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	—	—	V	V _{GS} = 0V, I _D = -250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	µA	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(th)}	-1.1	-1.6	-2.1	V	V _{DS} = V _{GS} , I _D = -250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	6.5	8	mΩ	V _{GS} = -10V, I _D = -10A
		—	7.2	10.2		V _{GS} = -4.5V, I _D = -10A
Forward Transfer Admittance	Y _{fs}	—	30	—	S	V _{DS} = -15V, I _D = -10A
Diode Forward Voltage	V _{SD}	—	-0.65	-1.0	V	V _{GS} = 0V, I _S = -1A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{iss}	—	6234	—	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	1500	—		
Reverse Transfer Capacitance	C _{rss}	—	774	—		
Gate Resistance	R _G	—	1.28	—	µ	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge	Q _g	—	59.2	—	nC	V _{DS} = -15V, V _{GS} = -4.5V, I _D = -10A
Gate-Source Charge	Q _{gs}	—	16.1	—		
Gate-Drain Charge	Q _{gd}	—	15.7	—		
Turn-On Delay Time	t _{D(on)}	—	11.4	—	ns	V _{DS} = -15V, V _{GEN} = -10V, R _G = 6Ω, I _D = -1A
Turn-On Rise Time	t _r	—	9.4	—		
Turn-Off Delay Time	t _{D(off)}	—	260.7	—		
Turn-Off Fall Time	t _f	—	99.3	—		

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 - UIS in production with L = 0.1mH, T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

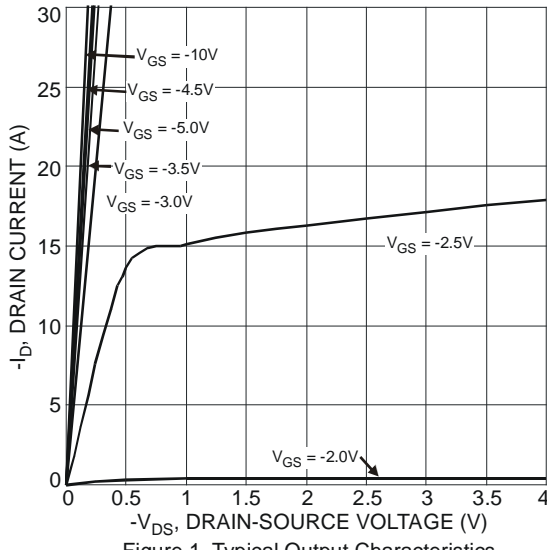


Figure 1 Typical Output Characteristics

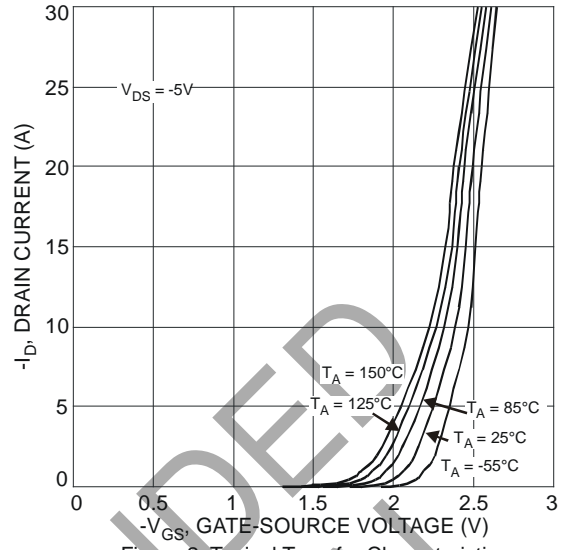


Figure 2 Typical Transfer Characteristics

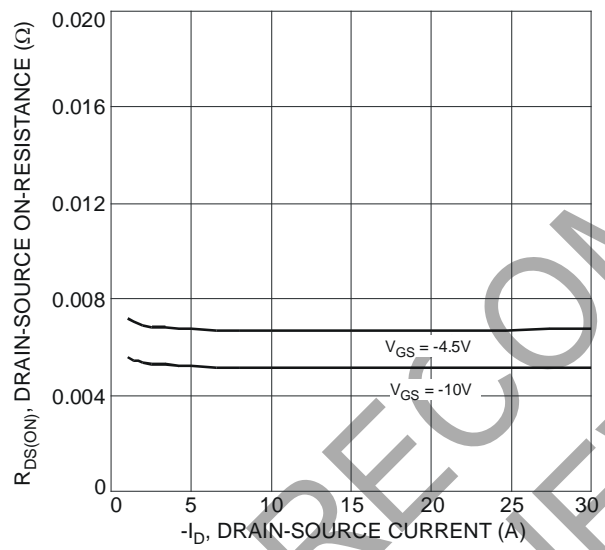


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

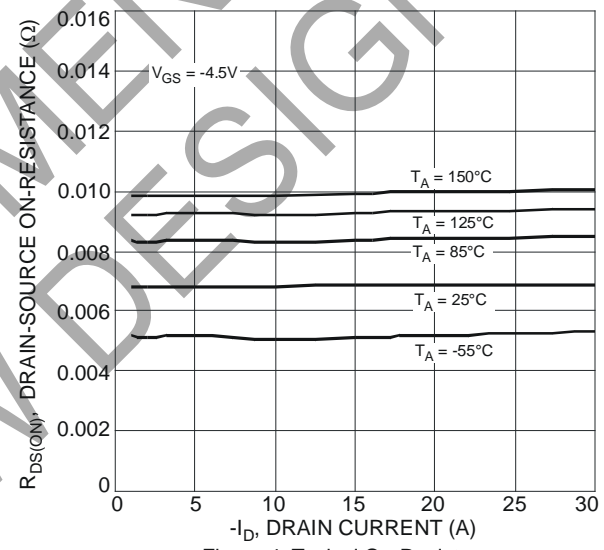


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

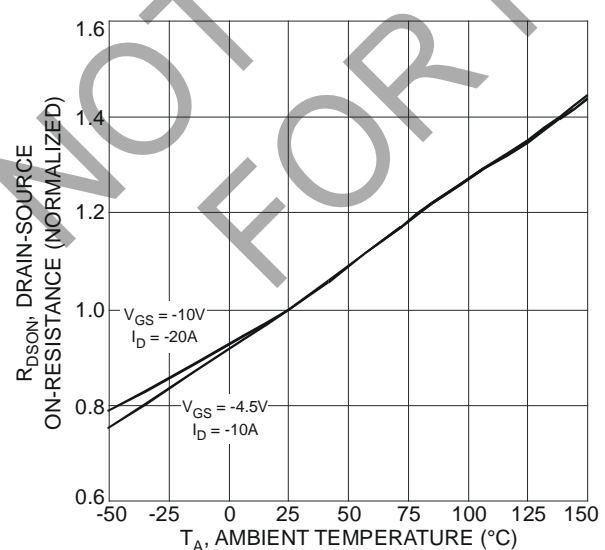


Figure 5 On-Resistance Variation with Temperature

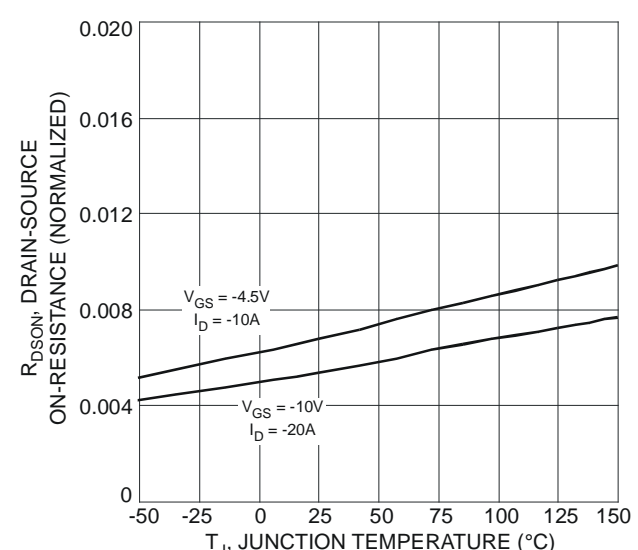


Figure 6 On-Resistance Variation with Temperature

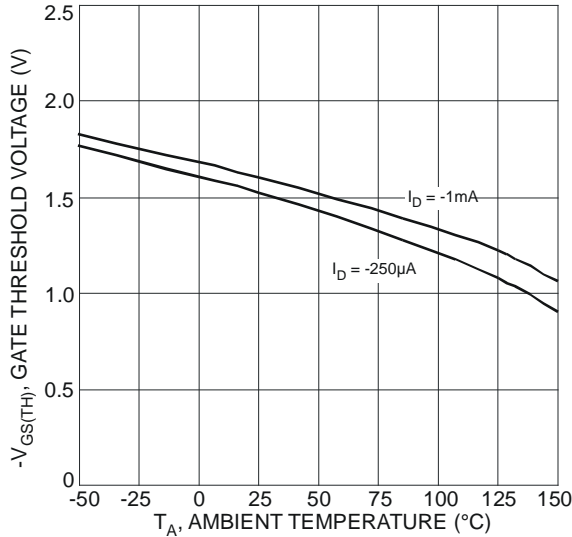


Figure 7 Gate Threshold Variation vs. Ambient Temperature

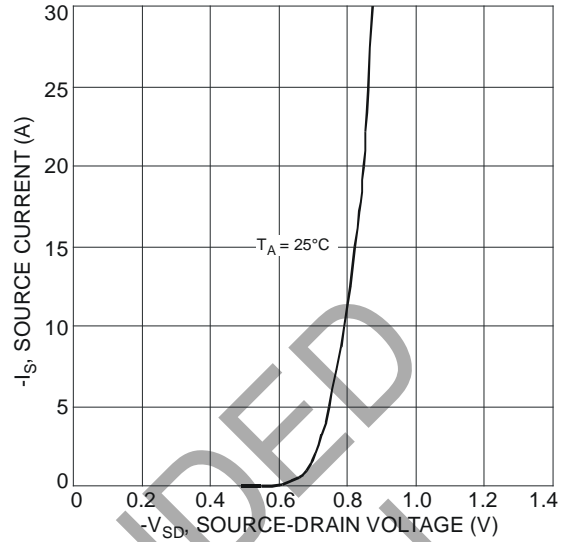


Figure 8 Diode Forward Voltage vs. Current

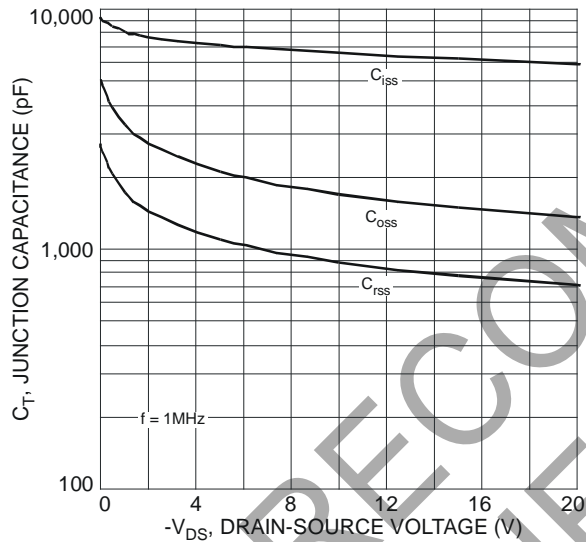


Figure 9 Typical Total Capacitance

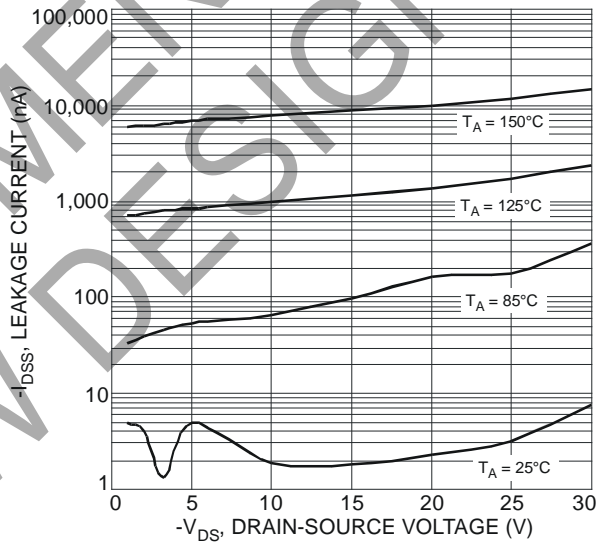


Figure 10 Typical Leakage Current vs. Drain-Source Voltage

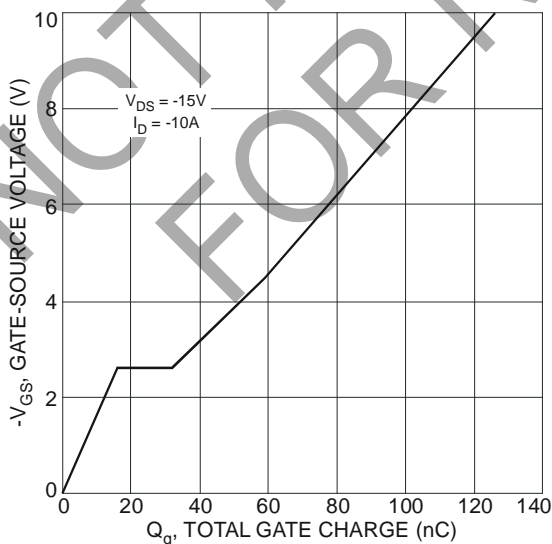


Figure 11 Gate-Source Voltage vs. Total Gate Charge

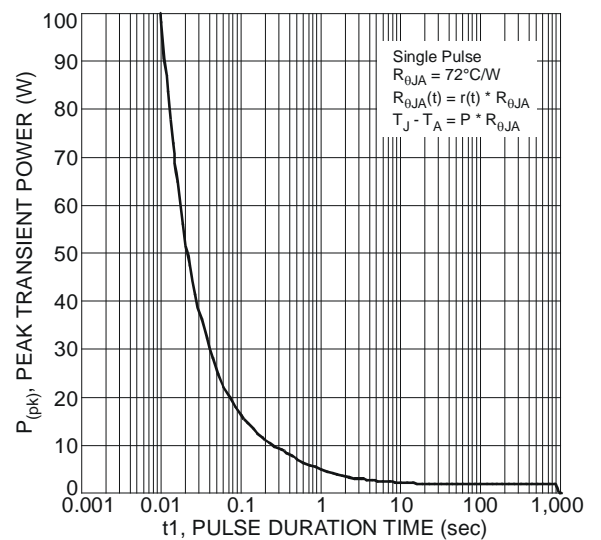


Figure 12 Single Pulse Maximum Power Dissipation

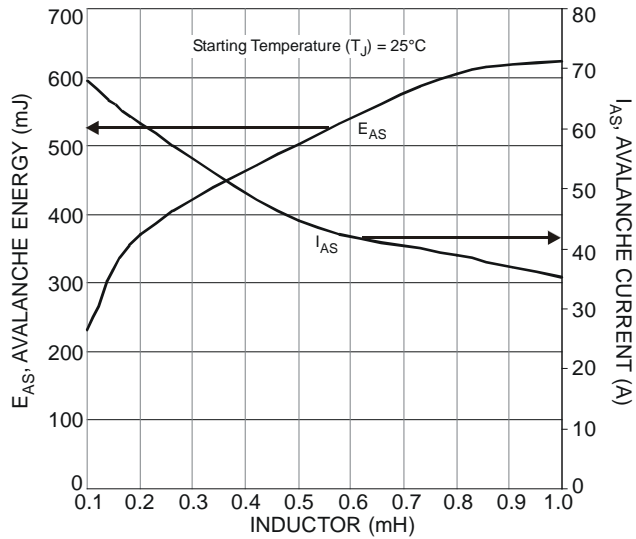


Figure 13 Single-Pulse Avalanche Tested

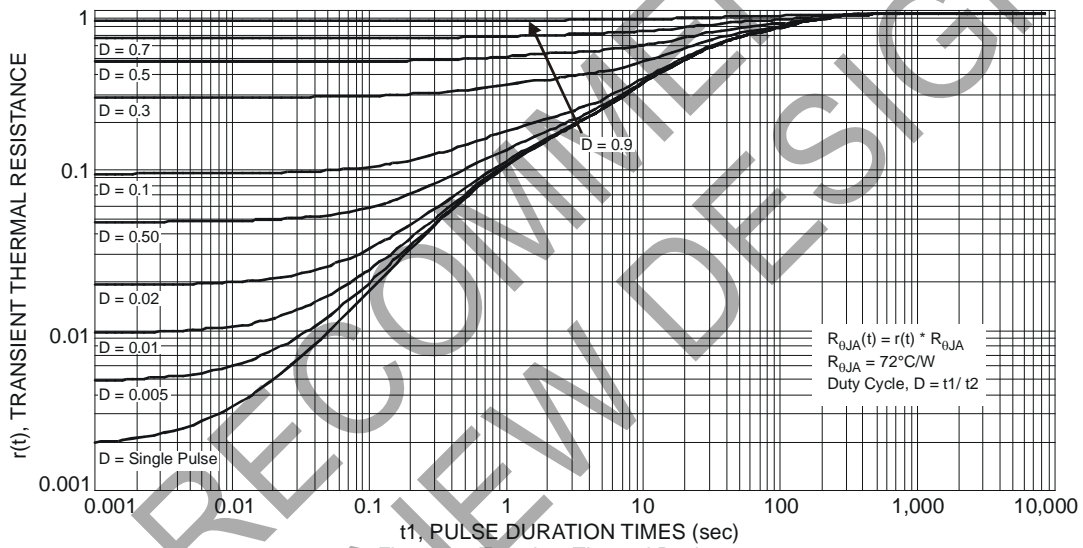


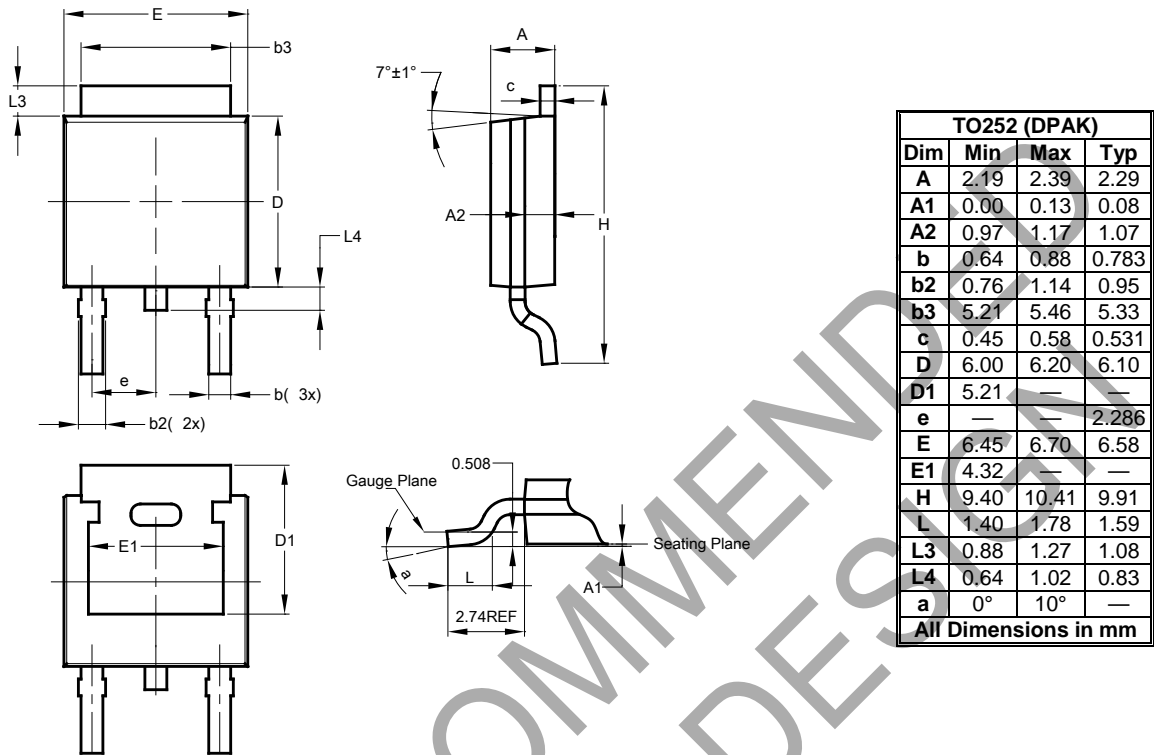
Figure 14 Transient Thermal Resistance

NOT RECOMMENDED FOR NEW DESIGN

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

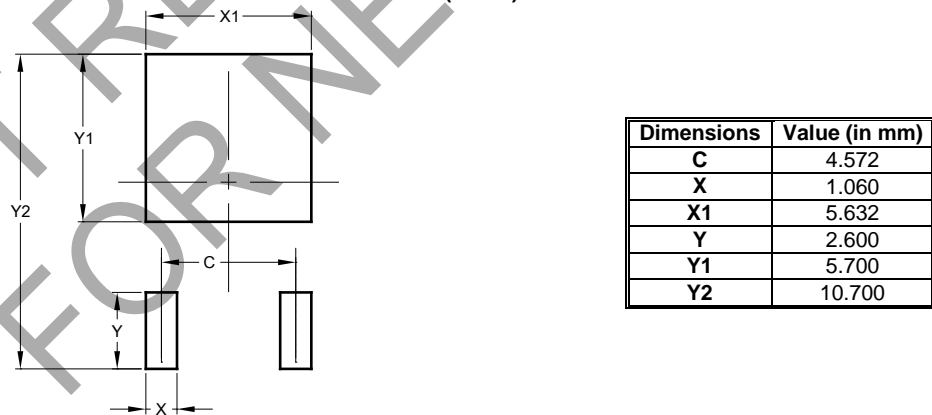
TO252 (DPAK)



Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO252 (DPAK)



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